

# HSF

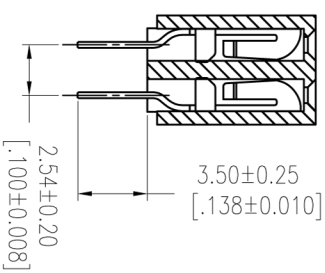
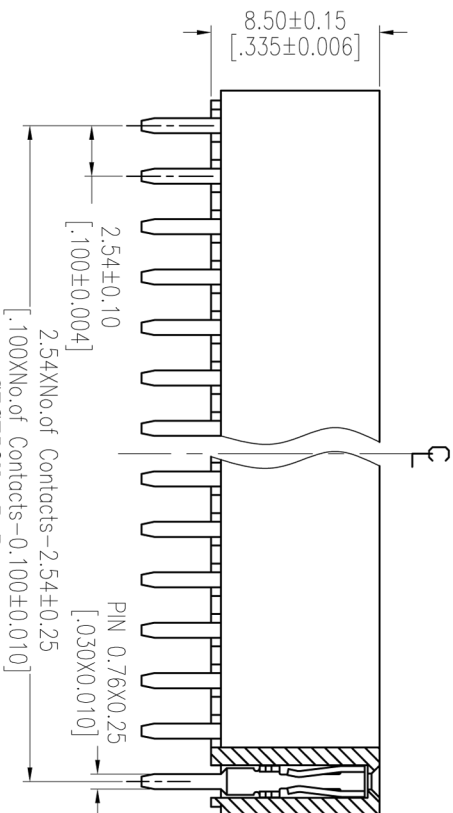
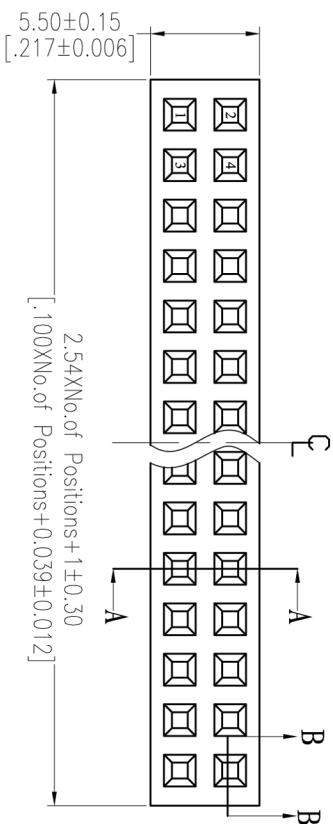
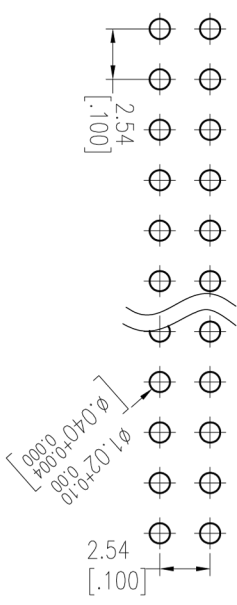
**NOTES:**

Current Rating: 3.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 1000V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze  
 Contact plating: Au Or Sn over Ni  
 Insulator Material: PA9T+30%G.F UL94V-0

**AA**

Recommended P.C.B Layout(Top Side)  
 (PCB BOARD TOLERANCE±0.05)



SECTION: A-A

## Ordering Information

2185-2XXSXXCUNT1

No. of Pins per ROW: 02-40PIN  
 Contact Plating: G0=Gold Flash, G3=10μ"Gold, G4=15μ"Gold, G5=30μ"Gold, S0=Gold Flash/Tin, S3=10μ"Gold/Tin, S4=15μ"Gold/Tin, S5=30μ"Gold/Tin, SN=Tin, SM=Matte Tin  
 Insulator: C=PA9T, T=Tube  
 Packing: T=Tube

Item	Pitch	Mating
Standard	2.54	1115/1120/1125
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A1	2013/03/15	Modify drawing	-----	XX	Wang	2013/03/15	mm	A4	2185-2XXSXXCUNT1
A0	2012/08/15	NEW	-----	X.XXX	CHECK	DATE	SIZE	SHEET	TITLE:
			-----	Angle	APPROVE	DATE	1/1	PROJ.	PH2.54mm DUAL ROW 180° DIP H=8.5
			-----	DIM					Customer NO.

**hf** 上海回峰电子科技有限公司  
 Shanghai Hui Feng Electronic Technology Co., Ltd.

电话: 021-67150229  
 传真: 021-67150251  
 企业邮箱: huiheng\_dzj@163.com  
 公司网站: www.huiheng-china.com